



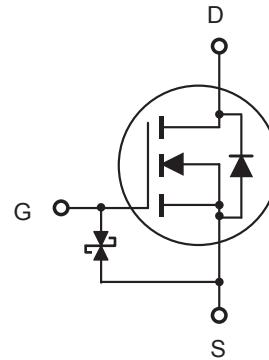
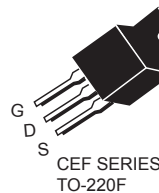
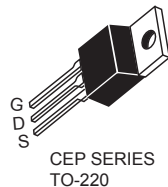
CEP02N6A/CEB02N6A CEF02N6A

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

Type	V _{DSS}	R _{DS(ON)}	I _D	@V _{GS}
CEP02N6A	600V	8.5Ω	1.4A	10V
CEB02N6A	600V	8.5Ω	1.4A	10V
CEF02N6A	600V	8.5Ω	1.4A ^d	10V

- Super high dense cell design for extremely low R_{DS(ON)}.
- High power and current handling capability.
- Lead free product is acquired.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V _{DS}	600		V
Gate-Source Voltage	V _{GS}	±30		V
Drain Current-Continuous	I _D	1.4	1.4 ^d	A
Drain Current-Pulsed ^a	I _{DM} ^e	5.6	5.6 ^d	A
Maximum Power Dissipation @ T _C = 25°C - Derate above 25°C	P _D	41	27	W
		0.33	0.22	W/°C
Operating and Store Temperature Range	T _J , T _{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R _{θJC}	3	4.5	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	65	°C/W



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CEF02N6A

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	600			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V$			25	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{GS} = 30V, V_{DS} = 0V$			10	μA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{GS} = -30V, V_{DS} = 0V$			-10	μA
On Characteristics ^b						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	2.5		4.2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 0.7A$		6.5	8.5	Ω
Dynamic Characteristics ^c						
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 0.7A$		0.9		S
Input Capacitance	C_{iss}	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0\text{ MHz}$		200		pF
Output Capacitance	C_{oss}			45		pF
Reverse Transfer Capacitance	C_{rss}			15		pF
Switching Characteristics ^c						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 300V, I_D = 1.4A, V_{GS} = 10V, R_{GEN} = 4.7\Omega$		14.8	29.6	ns
Turn-On Rise Time	t_r			14.2	28.4	ns
Turn-Off Delay Time	$t_{d(off)}$			25.2	50.4	ns
Turn-Off Fall Time	t_f			16.1	32.2	ns
Total Gate Charge	Q_g	$V_{DS} = 480V, I_D = 1.4A, V_{GS} = 10V$		5.9	8	nC
Gate-Source Charge	Q_{gs}			2.1		nC
Gate-Drain Charge	Q_{gd}			2.6		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S^f				1.4	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{GS} = 0V, I_S = 0.7A^g$			1.5	V
Notes : <input type="checkbox"/> a.Repetitive Rating : Pulse width limited by maximum junction temperature . b.Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$. <input type="checkbox"/> c.Guaranteed by design, not subject to production testing. <input type="checkbox"/> d.Limited only by maximum temperature allowed . e.Pulse width limited by safe operating area . f.Full package $I_{S(max)} = 1.1A$. g.Full package V_{SD} test condition $I_S = 1.1A$.						



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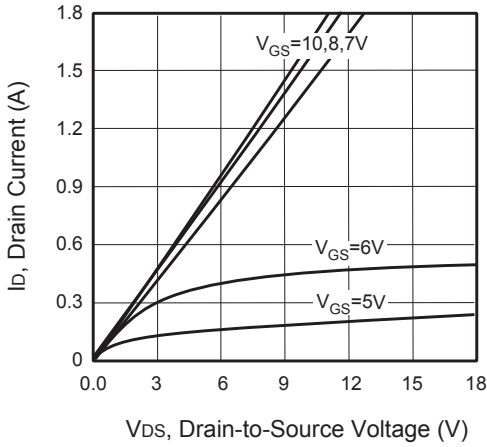


Figure 1. Output Characteristics

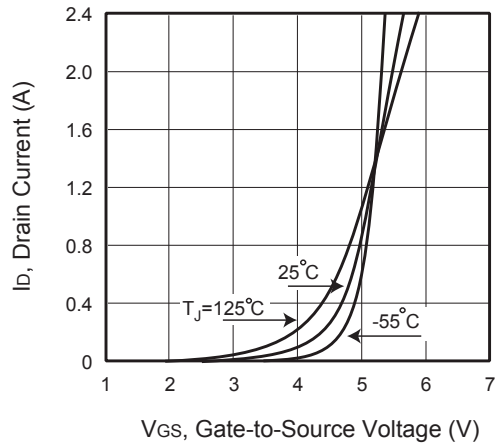


Figure 2. Transfer Characteristics

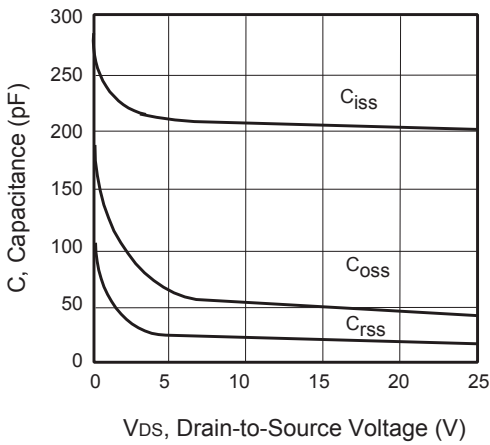


Figure 3. Capacitance

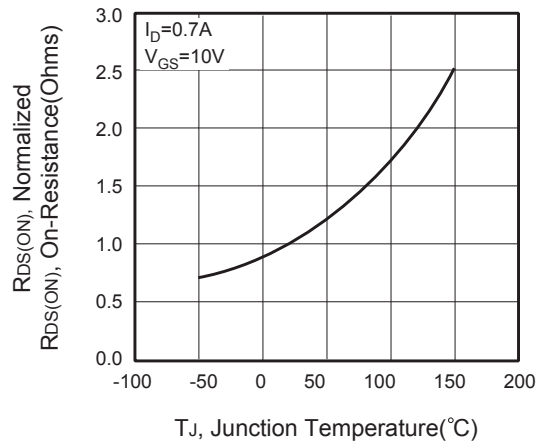


Figure 4. On-Resistance Variation with Temperature

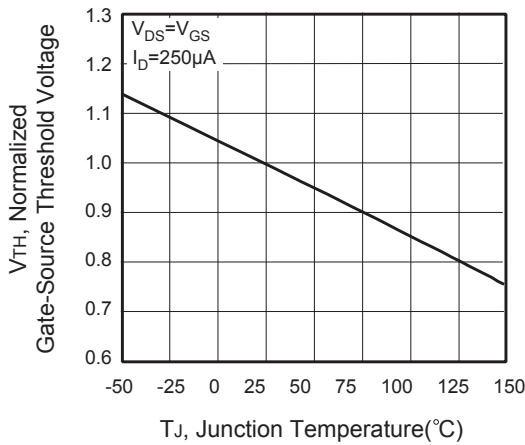


Figure 5. Gate Threshold Variation with Temperature

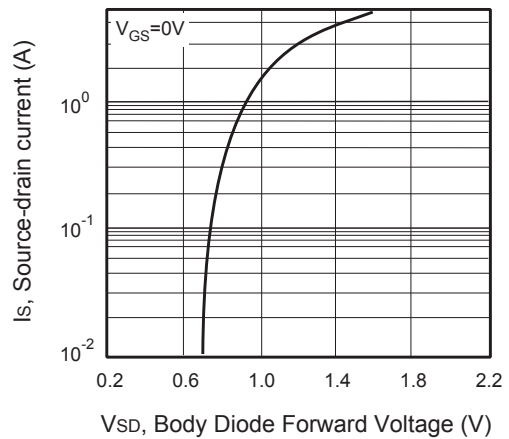


Figure 6. Body Diode Forward Voltage Variation with Source Current



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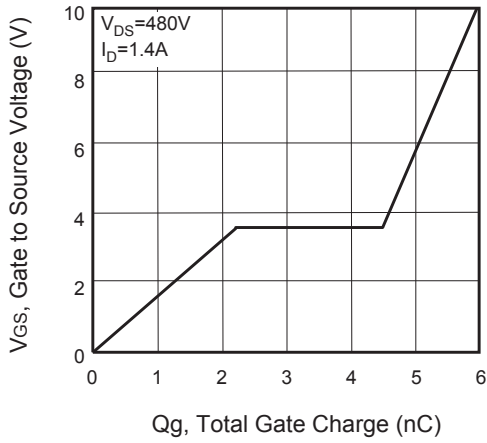


Figure 7. Gate Charge

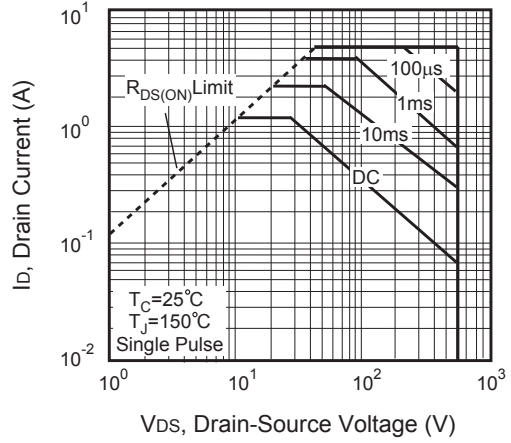


Figure 8. Maximum Safe Operating Area

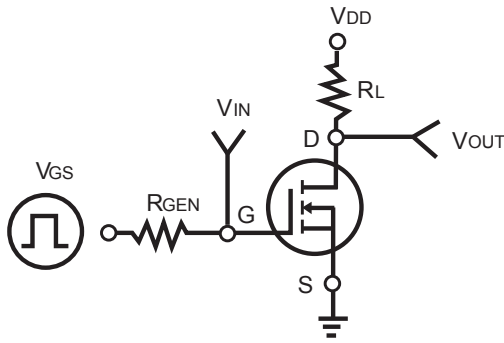


Figure 9. Switching Test Circuit

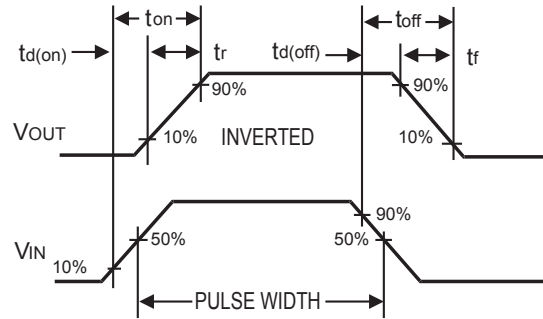


Figure 10. Switching Waveforms

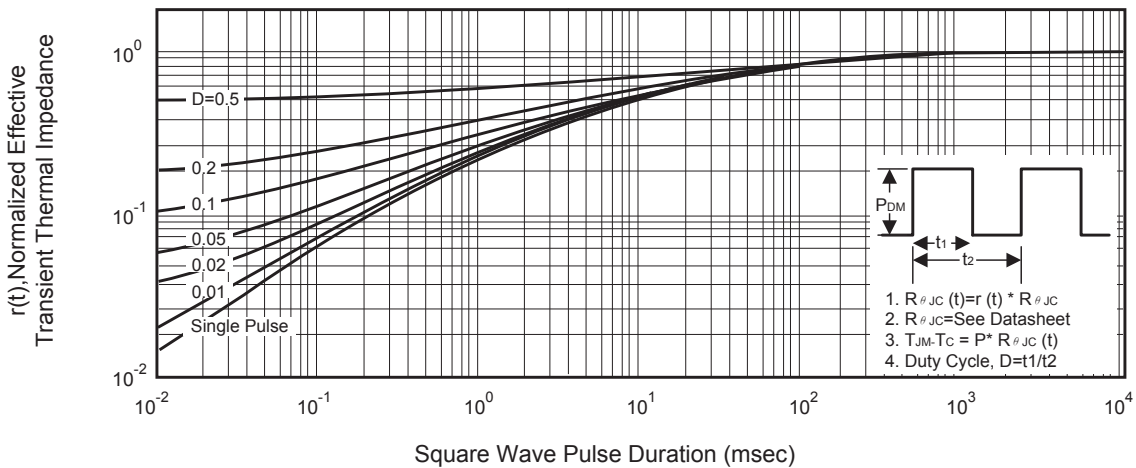


Figure 11. Normalized Thermal Transient Impedance Curve